What is claimed is:

1. An apparatus for bonding two optical disc substrates together by joining the optical disc substrates together with an adhesive and by curing the adhesive, which comprises an adhesive-supplying nozzle for supplying the adhesive onto at least one of the optical disc substrates, an electrode means placed in contact with or in the vicinity of the surface of the optical disc substrate which is opposite to the surface which faces the adhesive-supplying nozzle, and an electric power supply for generating an electric field between the electrode means and the adhesive-supplying nozzle.

2. The apparatus according to claim 1, wherein the adhesive-supplying nozzle comprises a single nozzle or two nozzles placed separated from each other by almost 180 degrees away from each other, is placed over the optical disc substrate nearly perpendicular thereto with its tip(s) pointing downward, and forms a ring-shaped adhesive liquid film on the optical disc substrate which spins relative to the nozzle(s).

3. The apparatus according to claim 1, wherein the adhesive-supplying nozzle comprises a plurality of nozzles placed at an approximately uniform spacing in a circular shape, is placed under the optical disc substrate nearly perpendicular thereto with their tips pointing upward, and supplies dot-shaped adhesive liquid films onto the underside of the optical disc substrate.

4. The apparatus according to claim 1, wherein the electric power supply generates an alternating-current electric field.

5. The apparatus according to claim 2, wherein the electric power supply generates an alternating-current electric field.

6. The apparatus according to claim 3, wherein the electric power supply generates an alternating-current electric field.

7. The apparatus according to claim 1, wherein the electric power supply generates a direct-current electric field.

8. The apparatus according to claim 2, wherein the electric power supply generates a direct-current electric field.

9. The apparatus according to claim 3, wherein the electric power supply generates a direct-current electric field.

10. The apparatus according to claim 1, wherein the electric power supply generates the electric field between the electrode means and the adhesive-supplying nozzle, so as to taper an end of a liquid film of the adhesive which is supplied by the adhesive-supplying nozzle toward the optical disc substrate in order to reduce an initial contact area between said end of the liquid film of the adhesive and the optical disc substrate for preventing generation of voids in said adhesive.

11. An optical disc bonding apparatus for joining two optical disc substrates together with an adhesive and forming an optical disc, the apparatus comprising: a device for forming an electric field between said two optical disc substrates, wherein

an end of a liquid film of said adhesive which is supplied onto one of said optical substrates tapers, thereby making a contact area between said end of said liquid film and the other of said optical disc substrates which is opposed to said end smaller by an effect of said electric field, and generation of voids in said liquid film is prevented.

12. An optical disc bonding apparatus for joining two optical disc substrates together with an adhesive and forming an optical disc, the apparatus comprising: a device for forming an electric field between said two optical disc substrates, wherein

an end of a liquid film of said adhesive which is supplied onto one of said optical substrates tapers, thereby making a contact area between said end of said liquid film and other liquid film of said adhesive which is supplied onto the other of said optical disc substrates and is opposed to said end smaller by an effect of said electric field, and generation of voids in said liquid film is prevented.